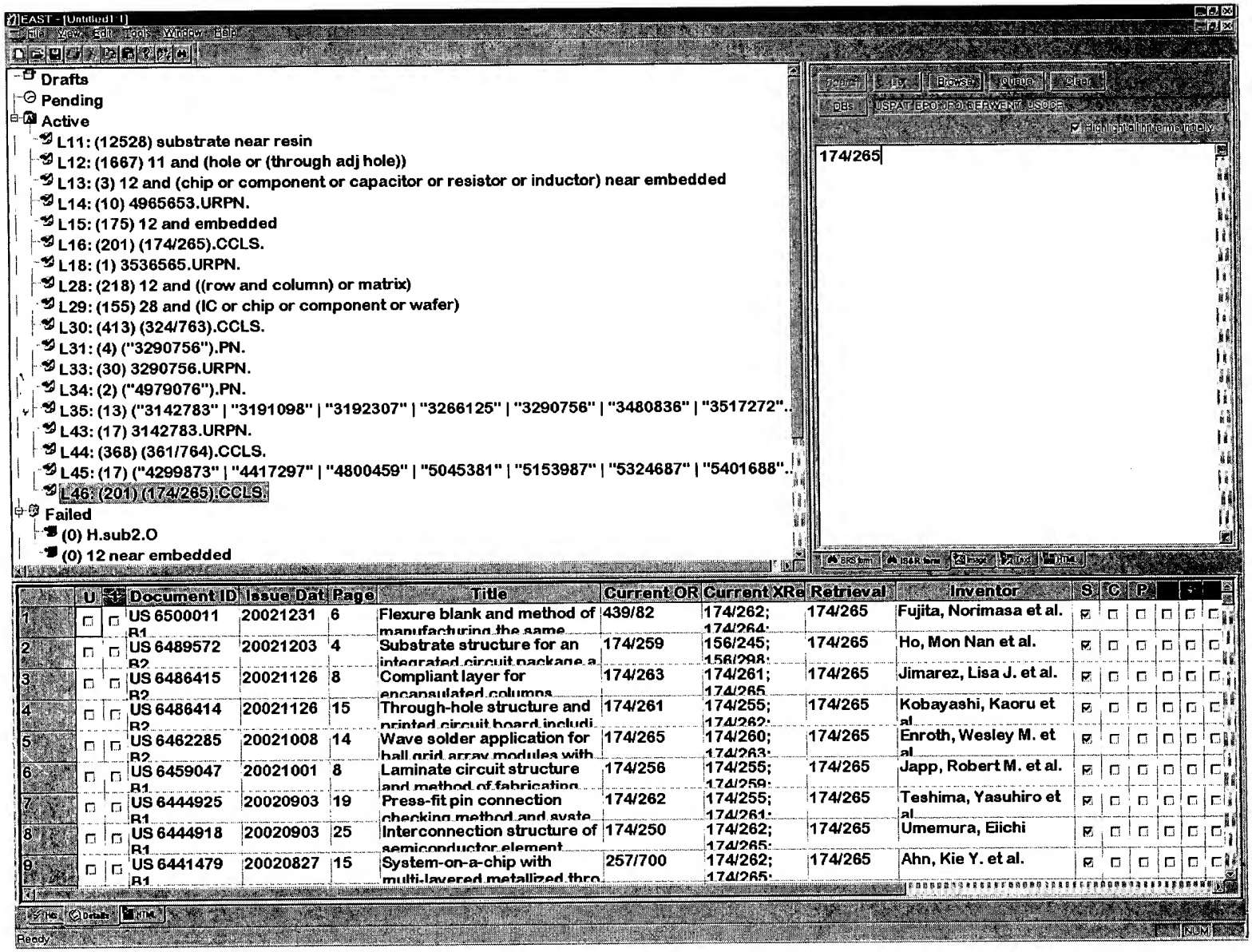

	U		Document ID	Issue Dat	Page	Title	Current OR	Current XRe	Retrieval	Inventor	S	C	P			
1	☐	☐	US 6500011 B1	20021231	6	Flexure blank and method of manufacturing the same	439/82	174/262; 174/264;	174/265	Fujita, Norimasa et al.	☑	☐	☐	☐	☐	☐
2	☐	☐	US 6489572 B2	20021203	4	Substrate structure for an integrated circuit package a	174/259	156/245; 156/298;	174/265	Ho, Mon Nan et al.	☑	☐	☐	☐	☐	☐
3	☐	☐	US 6486415 B2	20021126	8	Compliant layer for encapsulated columns	174/263	174/261; 174/265	174/265	Jimarez, Lisa J. et al.	☑	☐	☐	☐	☐	☐
4	☐	☐	US 6486414 B2	20021126	15	Through-hole structure and printed circuit board includi	174/261	174/255; 174/262;	174/265	Kobayashi, Kaoru et al.	☑	☐	☐	☐	☐	☐
5	☐	☐	US 6462285 B2	20021008	14	Wave solder application for ball grid array modules with	174/265	174/260; 174/263;	174/265	Enroth, Wesley M. et al.	☑	☐	☐	☐	☐	☐
6	☐	☐	US 6459047 B1	20021001	8	Laminate circuit structure and method of fabricating	174/256	174/255; 174/259;	174/265	Japp, Robert M. et al.	☑	☐	☐	☐	☐	☐
7	☐	☐	US 6444925 B1	20020903	19	Press-fit pin connection checking method and syste	174/262	174/255; 174/261;	174/265	Teshima, Yasuhiro et al.	☑	☐	☐	☐	☐	☐
8	☐	☐	US 6444918 B1	20020903	25	Interconnection structure of semiconductor element	174/250	174/262; 174/265;	174/265	Umemura, Eiichi	☑	☐	☐	☐	☐	☐
9	☐	☐	US 6441479 B1	20020827	15	System-on-a-chip with multi-layered metallized thro	257/700	174/262; 174/265;	174/265	Ahn, Kie Y. et al.	☑	☐	☐	☐	☐	☐